NSPM5131

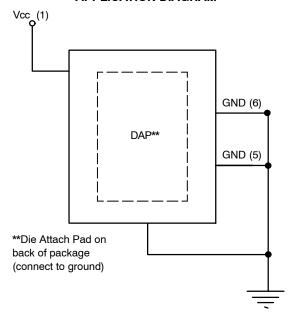
ESD Protection Diode

Low Clamping Voltage

Features

- Unidirectional High Voltage ESD Protection
- Provides ESD Protection to IEC61000-4-2 Level 4: ±30 kV Contact Discharge
- IEC 61000-4-5 (lighting)
- High Voltage Zener Diode Protects Supply Rail up to 160 A (8/20 µs)
- These Devices are Pb-Free and are RoHS Compliant

APPLICATION DIAGRAM





ON Semiconductor®

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UDFN6 CASE 517CS

BLOCK DIAGRAM



MARKING DIAGRAM



A3 = Specific Device Code
M = Date Code
Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
NSPM5131MUTBG	UDFN6	3000/Tape &
	(Pb-Free)	Reel

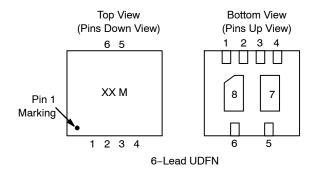
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NSPM5131

Table 1. PIN DESCRIPTIONS

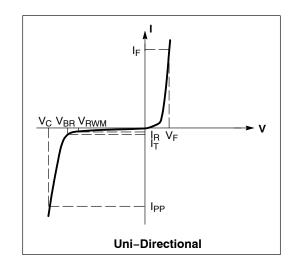
4-Channel, 6-Lead, UDFN-8 Package					
Pin	Name	Туре	Description		
1	V _{CC}	HV V _{DD}	HV ESD Channel		
2	N/C		No Connect		
3	N/C		No Connect		
4	N/C		No Connect		
5	GND		Ground		
6	GND		Ground		
7	GND		Ground		
8	GND		Ground		

PACKAGE / PINOUT DIAGRAMS



ELECTRICAL CHARACTERISTICS

Symbol	Parameter				
I _{PP}	Maximum Reverse Peak Pulse Current				
V _C	Clamping Voltage @ I _{PP}				
V _{RWM}	Working Peak Reverse Voltage				
I _R	Maximum Reverse Leakage Current @ V _{RWM}				
V _{BR}	Breakdown Voltage @ I _T				
Ι _Τ	Test Current				
ΘV _{BR}	Maximum Temperature Coefficient of V _{BR}				
I _F	Forward Current				
V _F	Forward Voltage @ I _F				



SPECIFICATIONS

Table 2. MAXIMUM RATINGS

Parameter	Rating	Units
Operating Temperature Range	-55 to +125	°C
Storage Temperature Range	-65 to +150	°C
Peak Current (t _p = 8/20 μs)	160	Α

Stresses at or above those listed in Maximum Ratings table may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Also, due to variations in test equipment, stresses shown above are averages.

ELECTRICAL CHARACTERISTICS

	V			Breakdown Voltage			V _C @ I _{PP} (8 x 20 μs) (Note 3)		
	Device	V _{RWM} (V) (Note 1)	I _R @ V _{RWM} (μ A)	V _{BR} V (Note 2)		@ I _T (mA)	V _C (V)	I _{PP} (A)	
Device Name	Marking	Max	Max	Min	Nom	Max		Max	
NSPM5131	A3	13.5	1	13.6	15.5	17.5	1	21.5	100

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 1. A transient suppressor is normally selected according to the working peak reverse voltage (V_{RWM}), which should be equal to or greater than the DC or continuous peak operating voltage level.
- 2. V_{BR} measured at pulse test current I_T at an ambient temperature of 25°C.
- 3. Surge current waveform per Figure 2.

NSPM5131

TYPICAL CHARACTERISTICS

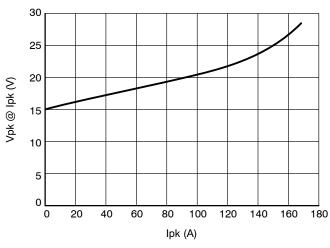


Figure 1. Clamping Voltage vs. Peak Pulse Current (t_p = 8/20 μ s)

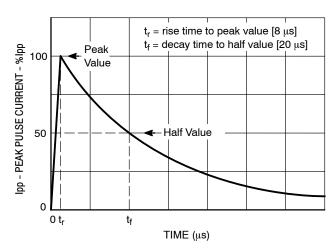
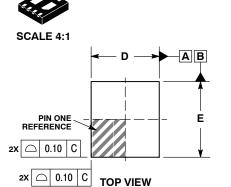
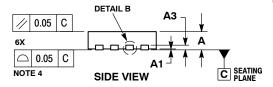


Figure 2. IEC61000-4-5 8/20 μs Pulse Waveform

DATE 30 APR 2013





DETAIL A

e1/2

2X D2 -

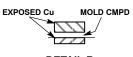
0.10 C

△ 0.10 C

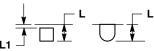
e1

BOTTOM VIEW

UDFN6, 1.8x2, 0.4P CASE 517CS **ISSUE 0**

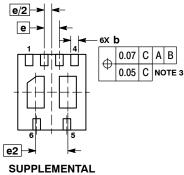


DETAIL B ALTERNATE CONSTRUCTION



ALTERNATE CONSTRUCTIONS





BOTTOM VIEW

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- 714.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION 6 APPLIES TO PLATED TERMINALS
 AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
 COPLANARITY APPLIES TO THE EXPOSED PAD
- AS WELL AS THE TERMINALS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.45	0.55		
A1	0.00	0.05		
A3	0.125 REF			
b	0.15	0.25		
D	1.80 BSC			
D2	0.35	0.55		
E	2.00 BSC			
E2	0.74 0.94			
е	0.40 BSC			
e1	0.80 BSC			
e2	0.95 BSC			
L	0.20 0.40			
L1	0.15			

GENERIC MARKING DIAGRAM*

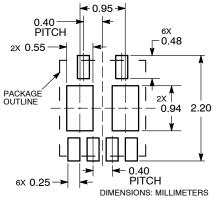


XX = Specific Device Code

= Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	UDFN6 1.8X2, 0.4P		PAGE 1 OF 1		

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